150 mA, Ultra Low Supply Current, Low Dropout Regulator

The NCP4682 and NCP4685 are CMOS Low Dropout Linear voltage regulators with 150 mA output current capability. The devices have high output voltage accuracy, a 1 μ A (typ.) ultra low supply current and high ripple rejection. Current fold-back protection is integrated in the devices to protect against over current and short current conditions. A Chip Enable (NCP4682 only) function is included to save power by further lowering supply current, which is advantageous for battery powered applications. The NCP4685 is optimized for the lowest quiescent current possible in applications where the device is always on.

Features

- Operating Input Voltage Range: 1.70 V to 5.25 V
- Output Voltage Range: 1.2 V to 3.3 V (available in 0.1 V steps)
- Output Voltage Accuracy: ±0.8%
- Excellent Output Voltage Temperature Coefficient : ±40 ppm/°C
- Supply Current: 1.0 µA (excluding CE pull down current)
- Standby Current: 0.1 µA
- Dropout Voltage: 0.24 V (I_{OUT} = 150 mA, V_{OUT} = 2.8 V)
- Line Regulation: 0.02%/V Typ.
- Stable with Ceramic Capacitors: 0.1 µF or more
- Current Fold Back Protection
- Available in UDFN4 1.0 x 1.0 mm, SC-82AB, SOT23 Packages
- These are Pb-Free Devices

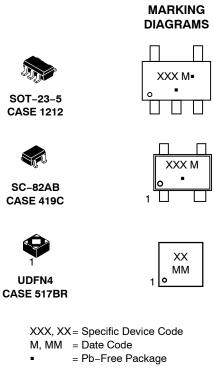
Typical Applications

- Battery-Powered Equipment
- Networking and Communication Equipment
- Cameras, DVRs, STB and Camcorders
- Home Appliances



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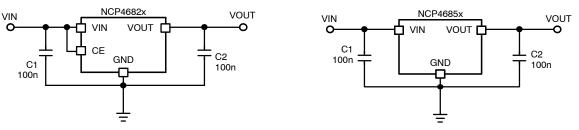
http://onsemi.com



(*Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 19 of this data sheet.





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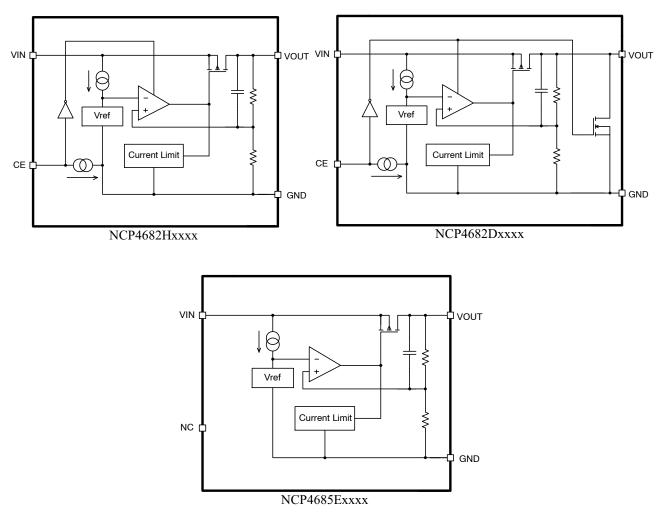


Figure 2. Simplified Schematic Block Diagram

PIN FUNCTION DESCRIPTION

Pin No. UDFN1010*	Pin No. SC-82AB	Pin No. SOT23	Pin Name	Description
1	3	5	V _{OUT}	Output pin
2	2	2	GND	Ground
3	1	3	CE/NC	Chip enable pin (Active "H") / No connection
4	4	1	V _{IN}	Input pin
-	-	4	NC	No connection

*Tab is GND level. (They are connected to the reverse side of this IC.) The tab is better to be connected to the GND, but leaving it open is also acceptable.

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input Voltage (Note 1)	V _{IN}	6.0	V
Output Voltage	V _{OUT}	–0.3 to VIN + 0.3	V
Chip Enable Input	V _{CE}	6.0	V
Output Current	I _{OUT}	200	mA

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Dissipation UDFN1010		400	
Power Dissipation SC-82AB	PD	380	mW
Power Dissipation SOT23		420	
Junction Temperature	TJ	-40 to 150	°C
Storage Temperature	T _{STG}	-55 to 125	°C
ESD Capability, Human Body Model (Note 2)	ESD _{HBM}	2000	V
ESD Capability, Machine Model (Note 2)	ESD _{MM}	200	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Refer to ELÉCTRICAL CHARACTERISTIS and APPLICATION INFORMATION for Safe Operating Area.

2. This device series incorporates ESD protection and is tested by the following methods:

ESD Human Body Model tested per AEC-Q100-002 (EIA/JESD22-A114)

ESD Machine Model tested per AEC-Q100-003 (EIA/JESD22-A115)

Latchup Current Maximum Rating tested per JEDEC standard: JESD78.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Characteristics, UDFN 1.0 x 1.0 mm Thermal Resistance, Junction-to-Air	$R_{\theta JA}$	250	°C/W
Thermal Characteristics, SOT23 Thermal Resistance, Junction-to-Air	$R_{\theta JA}$	238	°C/W
Thermal Characteristics, SC-82AB Thermal Resistance, Junction-to-Air	$R_{\theta JA}$	263	°C/W

ELECTRICAL CHARACTERISTICS

 $-40^{\circ}C \le T_A \le 85^{\circ}C$; $V_{IN} = V_{OUT(NOM)} + 1$ V or 2.5 V, whichever is greater; $I_{OUT} = 1$ mA, $C_{IN} = C_{OUT} = 0.1 \mu$ F, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.

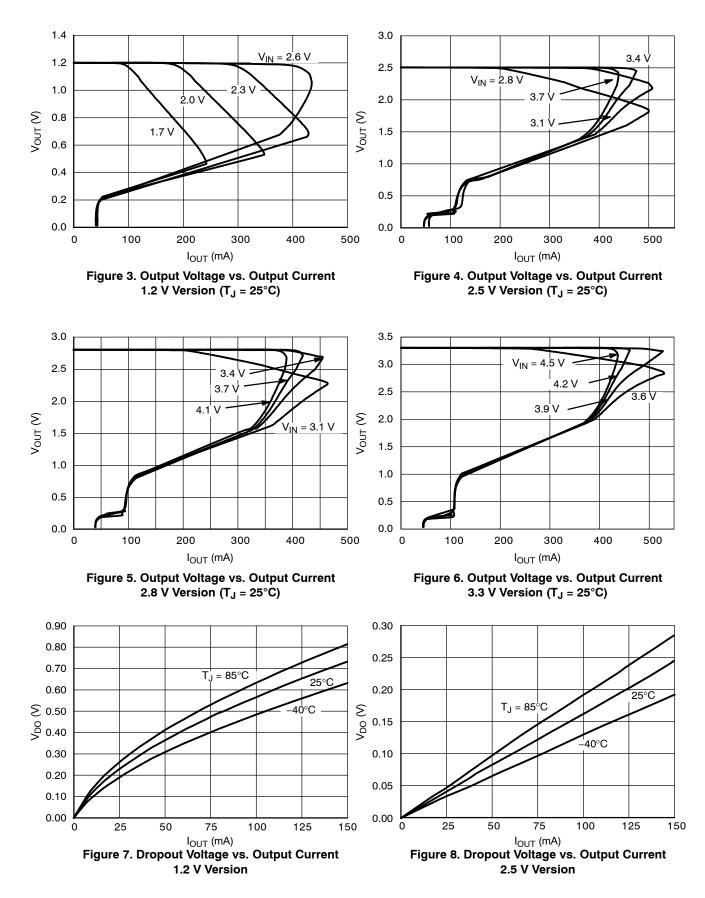
Parameter	Test Conditions		Symbol	Min	Тур	Max	Unit
Operating Input Voltage	(Note 3)		V _{IN}	1.70		5.25	V
Output Voltage	$T_A = +25 \ ^{\circ}C$ $V_{OUT} \ge 2.0 \ V$		V _{OUT}	x0.992		x1.008	V
		V _{OUT} < 2.0 V		-16		16	mV
	$-40^\circ C \leq T_A \leq 85^\circ C$	$V_{OUT} \ge 2.0 V$		x0.985		x1.015	V
		V _{OUT} < 2.0 V		-30		30	mV
Output Voltage Temp. Coefficient	$-40^\circ C \leq T_A \leq 85^\circ C$		ΔV _{OUT} / ΔT _A		±40		ppm/°C
Line Regulation	$V_{OUT(NOM)}$ + 0.5 V \leq V _{IN} \leq 5.0 V		Line _{Reg}		0.02	0.10	%/V
Load Regulation	loυτ = 1 m/	IOUT = 1 mA to 150 mA			10	20	mV
Dropout Voltage	l _{OUT} = 150 mA	$1.2~V \leq V_{OUT} < 1.5~V$	V _{DO}		0.76	1.05	V
		$1.5~V \leq V_{OUT} < 1.7~V$			0.53	0.80	
		$1.7~V \leq V_{OUT} < 2.0~V$			0.44	0.65	
		$2.0~\text{V} \leq \text{V}_{OUT} < 2.5~\text{V}$			0.34	0.50	
		$2.5~V \leq V_{OUT} < 2.8~V$			0.28	0.40	
		$2.8~V \leq V_{OUT} < 3.3~V$			0.24	0.32	
Output Current		•	I _{OUT}	150			mA
Short Current Limit	V _{OUT}	- = 0 V	I _{SC}		40		mA
Quiescent Current			l _Q		1.0	1.5	μΑ

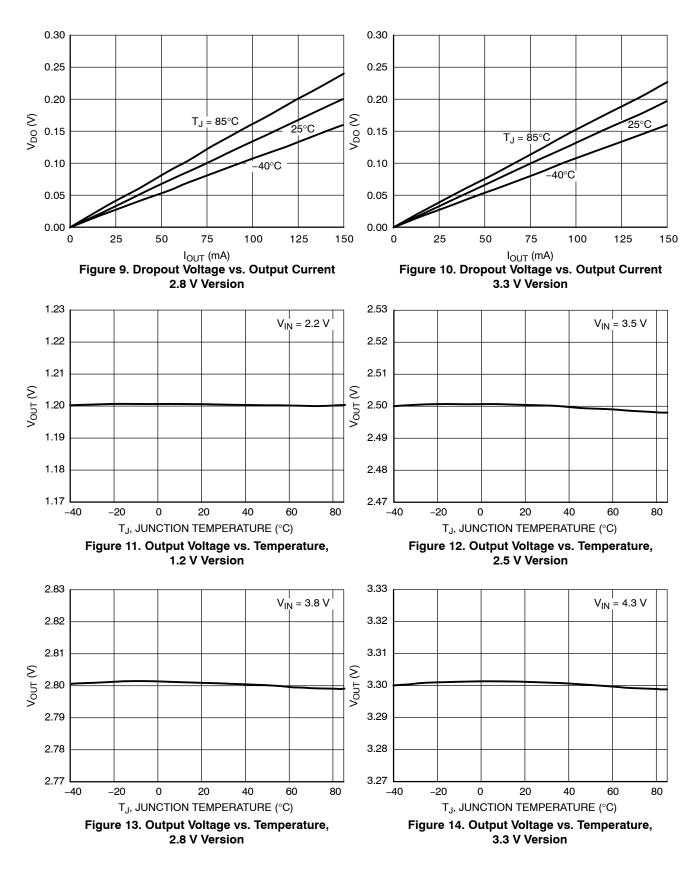
ELECTRICAL CHARACTERISTICS

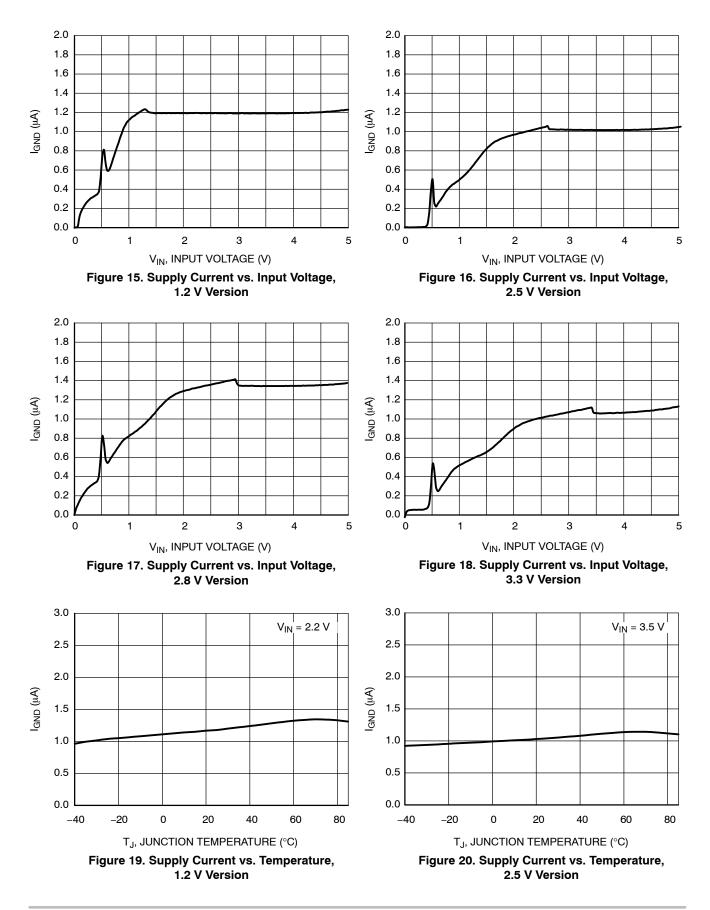
 $-40^{\circ}C \le T_A \le 85^{\circ}C$; $V_{IN} = V_{OUT(NOM)} + 1$ V or 2.5 V, whichever is greater; $I_{OUT} = 1$ mA, $C_{IN} = C_{OUT} = 0.1 \ \mu$ F, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.

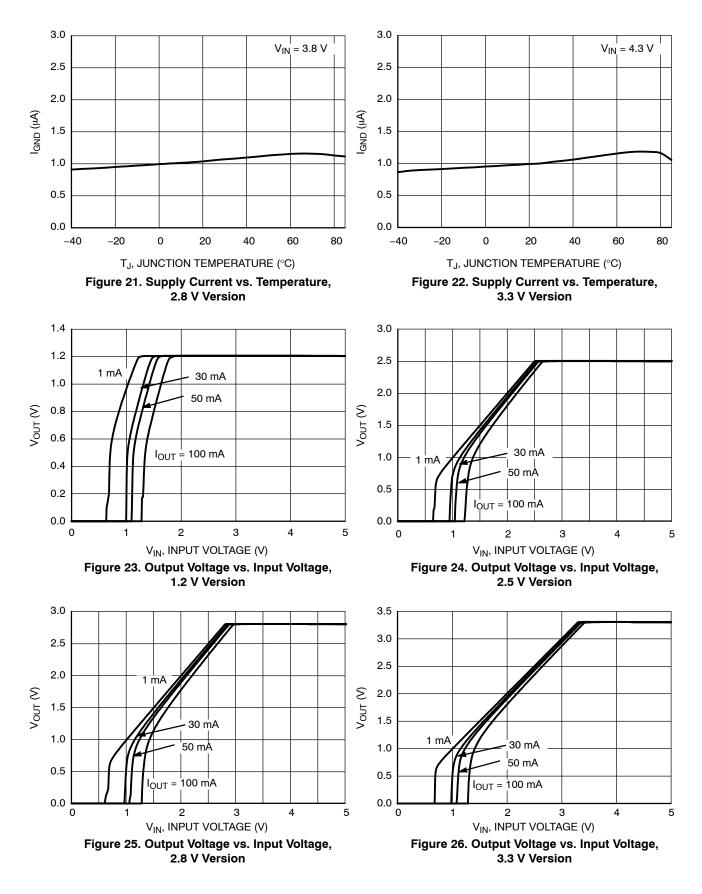
Parameter Test Conditions		Symbol	Min	Тур	Max	Unit
Standby Current	V_{CE} = 0 V, T_A = 25°C, NCP4682 only	I _{STB}		0.1	1.0	μΑ
CE Pin Threshold Voltage	CE Input Voltage "H"	V _{CEH}	1.5			V
(NCP4682 only)	CE Input Voltage "L"	V _{CEL}			0.3	
CE Pull Down Current	t NCP4682 only			0.3		μΑ
ower Supply Rejection Ratio $ \begin{array}{l} V_{IN} = 2.2 \ V, \ V_{OUT} = 1.2 \ V, \ \Delta V_{IN} = 0.2 \ V_{pk-pk}, \\ I_{OUT} = 30 \ mA, \ f = 1 \ kHz \end{array} $		PSRR		30		dB
Output Noise Voltage	f = 10 Hz to 100 kHz, I_{OUT} = 30 mA, V_{OUT} = 1.2 V, V_{IN} = 2.2 V	V _N		70		μV _{rms}
Low Output Nch Tr. On Resistance	V_{IN} = 4 V, V_{CE} = 0 V, NCP4682D only	R _{LOW}		30		Ω

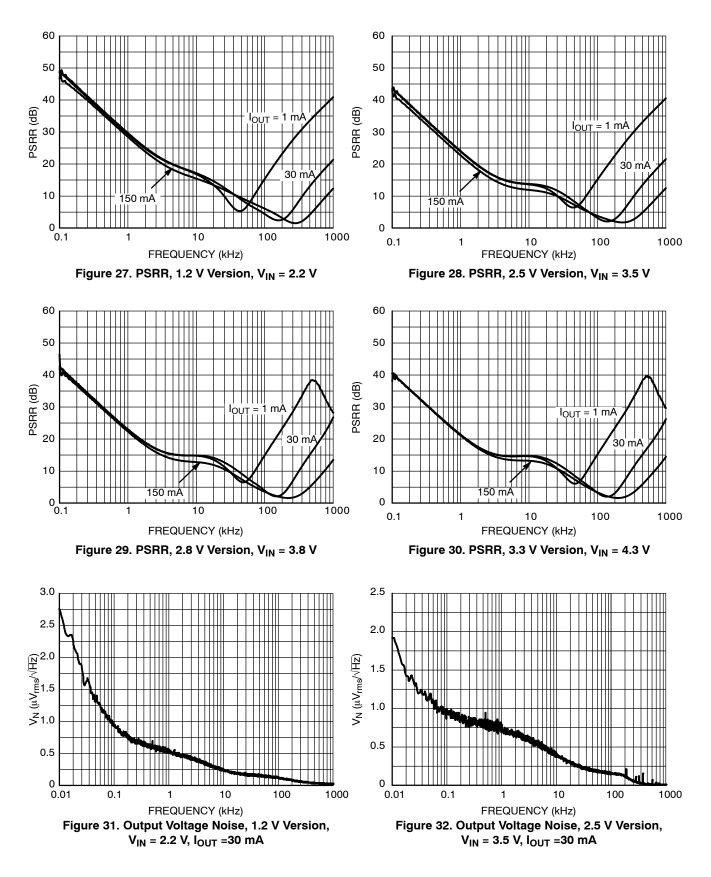
3. The maximum Input Voltage of the Electrical Characteristics is 5.25 V. In case of exceeding this specification, the IC must be operated n condition that the Input Voltage is up to 5.50 V and total operation time is within 500 hours.

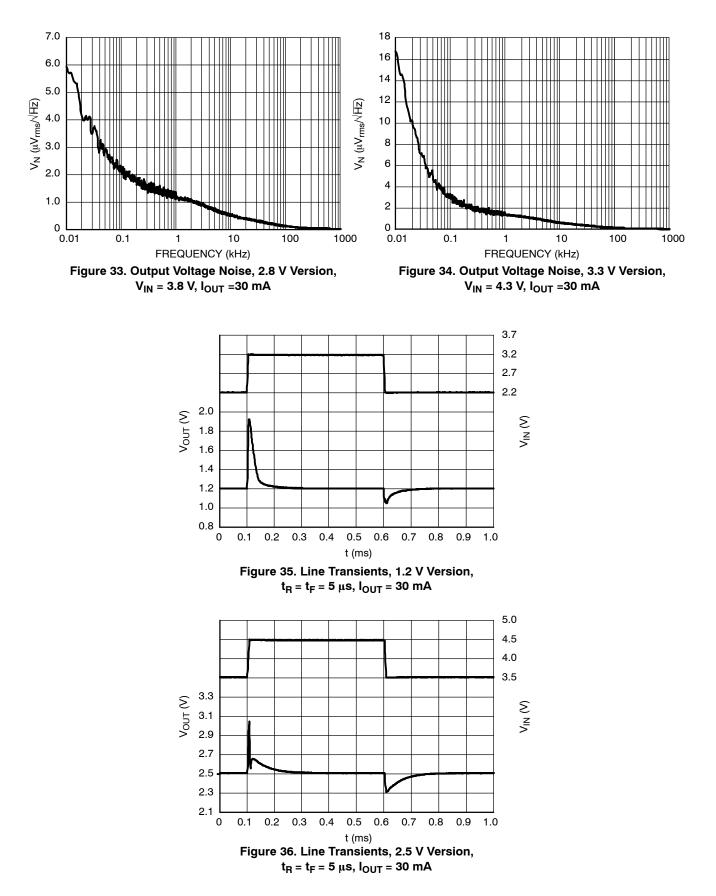


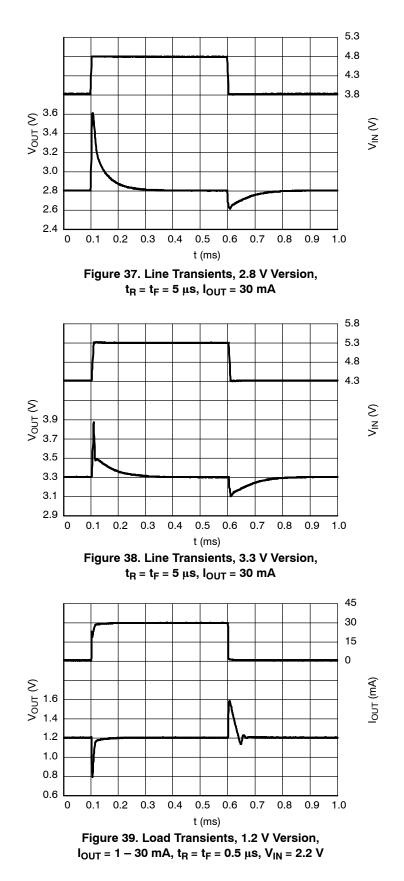


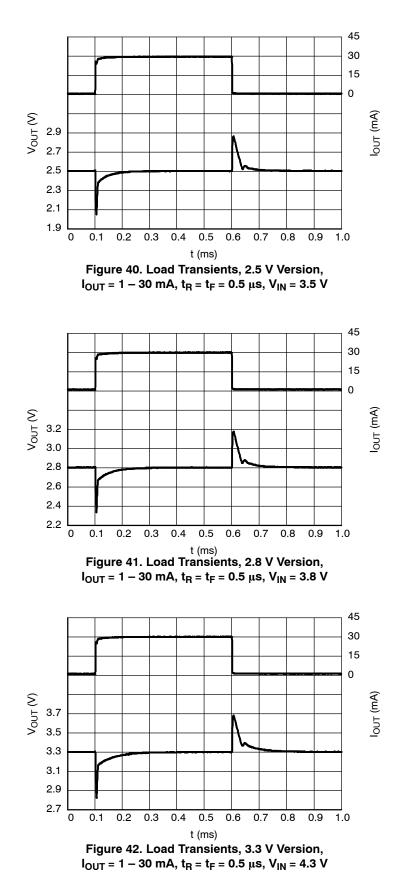


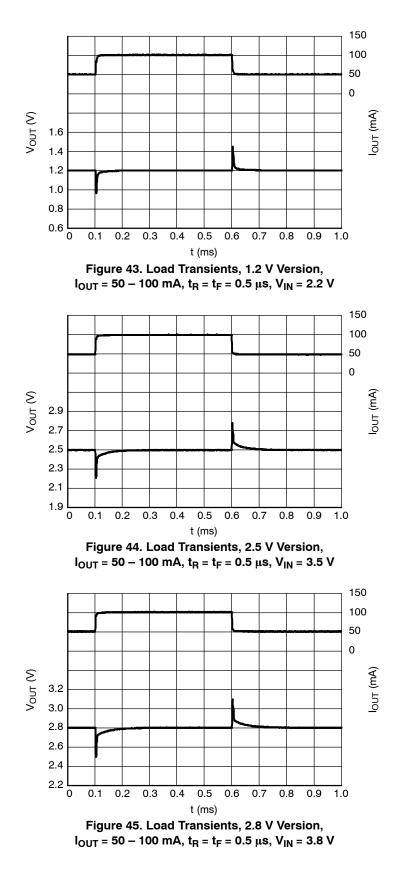


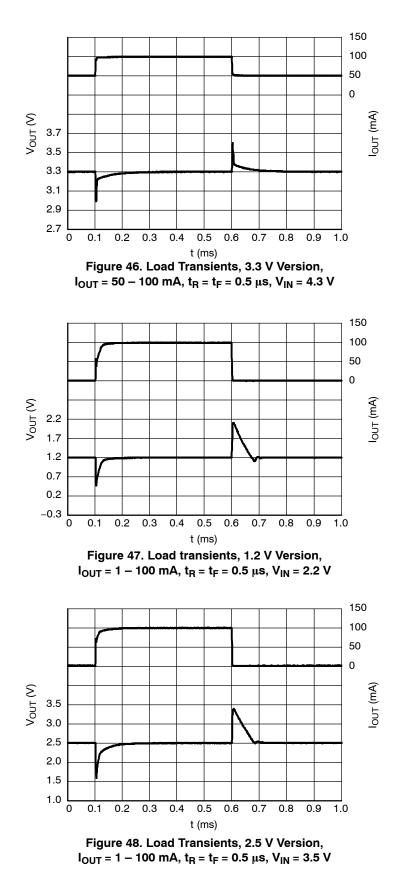


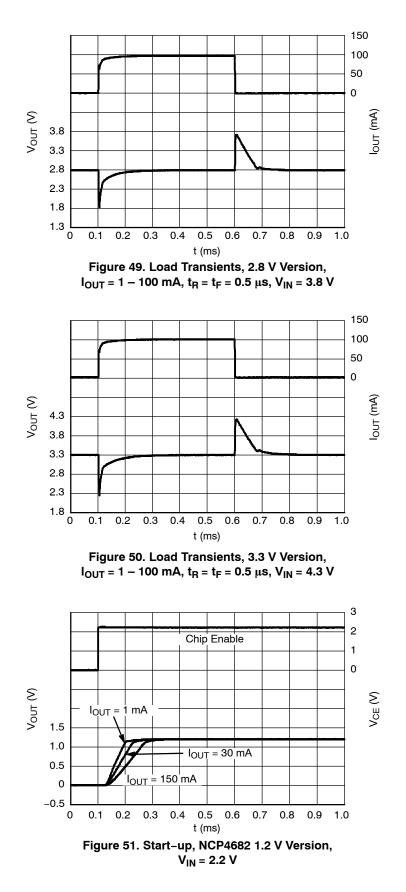


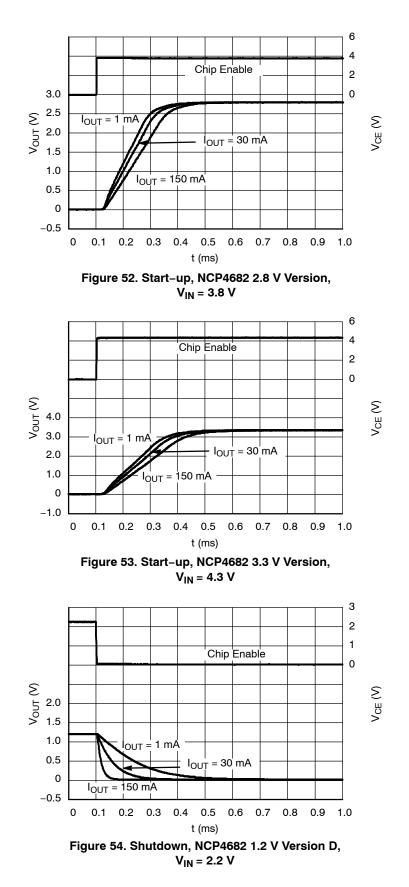


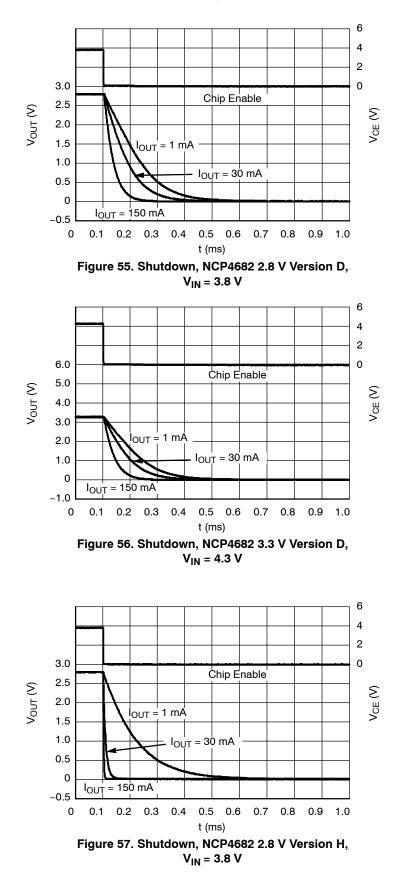












APPLICATION INFORMATION

A typical application circuits for NCP4682 and NCP4685 series is shown in Figure 58.

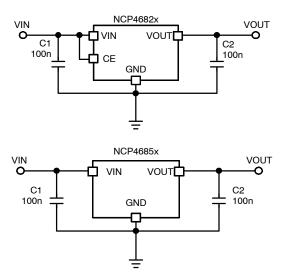


Figure 58. Typical Application Schematic

Input Decoupling Capacitor (C1)

A 0.1 μ F ceramic input decoupling capacitor should be connected as close as possible to the input and ground pin of the NCP4682/5. Higher values and lower ESR improves line transient response.

Output Decoupling Capacitor (C2)

A 0.1 μ F ceramic output decoupling capacitor is enough to achieve stable operation of the IC. If a tantalum capacitor is used, and its ESR is high, loop oscillation may result. The capacitors should be connected as close as possible to the output and ground pins. Larger values and lower ESR improves dynamic parameters.

Current Limit

This regulator includes a fold-back current limiting circuit. This type of protection doesn't limit output current

up to specified current capability in normal operation, but when an over current situation occurs, the output voltage and current decrease until the over current condition ends. Typical characteristics of this protection scheme are shown in the Output voltage versus Output current graphs in the characterization section of this datasheet.

Enable Operation (NCP4682 Only)

The enable pin CE may be used for turning the regulator on and off. The IC is switched on when a high level voltage is applied to the CE pin. The enable pin has an internal pull down current source. If the enable function is not needed, connect CE pin to VIN.

Output Discharger (NCP4682 Only)

The NCP4682D version includes a transistor between VOUT and GND that is used for faster discharging of the output capacitor. This function is activated when the IC goes into disable mode.

Thermals

As a power across the IC increase, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and also the ambient temperature affect the rate of temperature increase for the part. When the device has good thermal conductivity through the PCB the junction temperature will be relatively low in high power dissipation applications.

PCB layout

Make the VIN and GND line as large as practical. If their impedance is high, noise pickup or unstable operation may result. Connect capacitors C1 and C2 as close as possible to the IC, and make wiring as short as possible.

ORDERING INFORMATION

Device	Nominal Output Voltage	Description	Marking	Package	Shipping	
NCP4682DMU12TCG	1.2 V	Auto discharge	CA			
NCP4682DMU15TCG	1.5 V	Auto discharge	CC			
NCP4682DMU18TCG	1.8 V	Auto discharge	CD			
NCP4682DMU19TCG	1.9 V	Auto discharge	CF			
NCP4682DMU25TCG	2.5 V	Auto discharge	СН			
NCP4682DMU28TCG	2.8 V	Auto discharge	CL	UDFN4		
NCP4682DMU30TCG	3.0 V	Auto discharge	CP	(Pb-Free)	10000 / Tape & Reel	
NCP4682DMU33TCG	3.3 V	Auto discharge	CR			
NCP4682HMU18TCG	1.8 V	Enable high	AD			
NCP4682HMU28TCG	2.8 V	Enable high	AL			
NCP4682HMU33TCG	3.3 V	Enable high	AR			
NCP4685EMU30TCG	3.0 V	Without enable	BP			
NCP4682DSN30T1G	3.0 V	Auto discharge	92P	SOT-23-5		
NCP4682DSN33T1G	3.3 V	Auto discharge	92R	(Pb-Free)	3000 / Tape & Reel	
NCP4682DSQ12T1G	1.2 V	Auto discharge	R0			
NCP4682DSQ15T1G	1.5 V	Auto discharge	R2			
NCP4682DSQ18T1G	1.8 V	Auto discharge	R3			
NCP4682DSQ20T1G	2.0 V	Auto discharge	R6			
NCP4682DSQ25T1G	2.5 V	Auto discharge	R7	SC-82AB		
NCP4682DSQ28T1G	2.8 V	Auto discharge	S0	(Pb-Free)	3000 / Tape & Reel	
NCP4682DSQ33T1G	3.3 V	Auto discharge	S5			
NCP4685ESQ15T1G	1.5 V	Without enable	N2			
NCP4685ESQ25T1G	2.5 V	Without enable	N7			
NCP4685ESQ33T1G	3.3 V	Without enable	P5	1		

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*To order other package and voltage variants, please contact your ON Semiconductor sales representative.

D

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DATE 28 JAN 2011





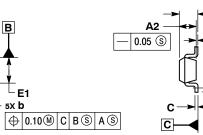
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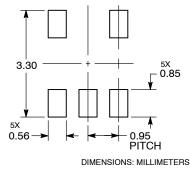
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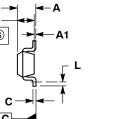
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*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



SOT-23 5-LEAD CASE 1212-01 ISSUE A

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		MILLIN	IETERS	
	DIM	MIN	MAX	
	Α		1.45	
	A1	0.00	0.10	
	A2	1.00	1.30	
	b	0.30	0.50	
	C	0.10	0.25	
	D	2.70	3.10	
	Е	2.50	3.10	
	E1	1.50	1.80	
	е	0.95	BSC	
	L	0.20		
	L1	0.45	0.75	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

- M = Date Code
- = Pb–Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ■", may or may not be present.

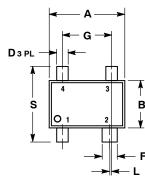
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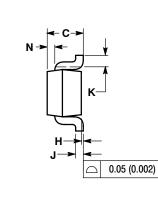
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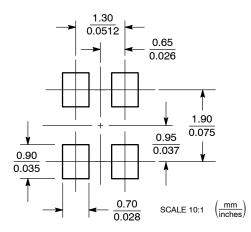
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SC-82AB CASE 419C-02 **ISSUE F**

SOLDERING FOOTPRINT*



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NOTES:

 NOTES:
DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: MILLIMETER.
419C-01 OBSOLETE. NEW STANDARD IS 419C-02.
DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURDS BURRS.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.80	2.20	0.071	0.087
В	1.15	1.35	0.045	0.053
С	0.80	1.10	0.031	0.043
D	0.20	0.40	0.008	0.016
F	0.30	0.50	0.012	0.020
G	1.10	1.50	0.043	0.059
Н	0.00	0.10	0.000	0.004
J	0.10	0.26	0.004	0.010
K	0.10		0.004	
L	0.05	0.05 BSC		BSC
Ν	0.20	0.20 REF		REF
S	1.80	2.40	0.07	0.09

GENERIC **MARKING DIAGRAM***



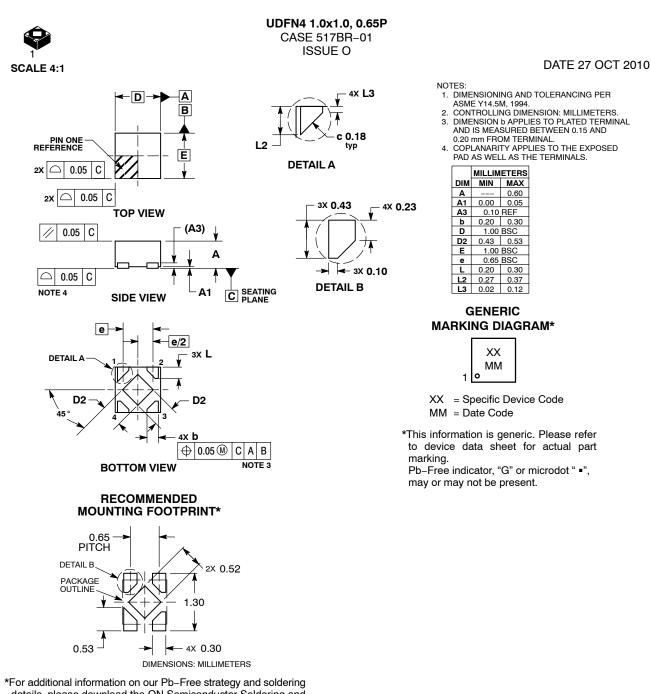
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= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present.

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